



PUBLICLY AVAILABLE SPECIFICATION PRE-STANDARD



**Connectors for electrical and electronic equipment – Tests and measurements –
Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on
IEC 60603-7 series connectors – Tests 27a to 27g**

INTERNATIONAL
ELECTROTECHNICAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

CONNECTORS FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – TESTS AND MEASUREMENTS –

Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on IEC 60603-7 series connectors – Tests 27a to 27g

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IEC PAS 60512-27-200 has been processed by subcommittee 48B: Electrical connectors, of IEC technical committee 48: Electrical connectors and mechanical structures for electrical and electronic equipment.

The text of this PAS is based on the following document:

This PAS was approved for publication by the P-members of the committee concerned as indicated in the following document

Draft PAS	Report on voting
48B/2652/DPAS	48B/2673/RVDPAS

Following publication of this PAS, which is a pre-standard publication, the technical committee or subcommittee concerned may transform it into an International Standard.

A list of all parts of IEC 60512 series, under the general title *Connectors for electrical and electronic equipment – Tests and measurements* can be found on the IEC website.

Future standards in this series will carry the new general title as cited above. Titles of existing standards in this series will be updated at the time of the next edition.

This PAS shall remain valid for an initial maximum period of 3 years starting from the publication date. The validity may be extended for a single period up to a maximum of 3 years, at the end of which it shall be published as another type of normative document, or shall be withdrawn.

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CONNECTORS FOR ELECTRICAL AND ELECTRONIC EQUIPMENT – TESTS AND MEASUREMENTS –

Part 27-200: Additional specifications for signal integrity tests up to 2 000 MHz on IEC 60603-7 series connectors – Tests 27a to 27g

1 Scope

This part of IEC 60512 covers additional, supplemental specifications for signal integrity and transmission performance test methods of IEC 60512-27-100, for connectors using de-embedded crosstalk measurements, which are specified in respective parts of IEC 60603-7 standards for connecting hardware applications up to 2 000 MHz.

These additional specifications are also applicable for testing the related lower frequency connectors. However, the test methodology specified in the detail specification for any given connector remains the reference conformance test for that connector.

Test procedures of IEC 60512-27-100 affected by these supplemental methods and procedures are:

- insertion loss, test 27a;
- return loss, test 27b;
- near-end crosstalk (NEXT) test 27c;
- far-end crosstalk (FEXT), test 27d;
- transverse conversion loss (TCL), test 27f;
- transverse conversion transfer loss (TCTL), test 27g.

Other test procedures referenced here are:

- transfer impedance (Z_T), see test procedures in IEC 62153-4-6 or IEC 62153-4-7.
- for coupling attenuation (a_C), see test procedures in IEC 62153-4-7 or IEC 62153-4-12.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 60050-581, *International Electrotechnical Vocabulary (IEV) – Part 581: Electromechanical components for electronic equipment*

IEC 60512-1, *Connectors for electronic equipment – Tests and measurements – Part 1: General*

IEC 60512-26-100, *Connectors for electronic equipment – Tests and measurements – Part 26-100: Measurement setup, test and reference arrangement and measurements for connectors according to IEC 60603-7 – Tests 26a to 26g*

IEC 60512-27-100, *Connectors for electronic equipment – Tests and measurements – Part 27-100: Signal integrity tests up to 500 MHz on 60603-7 series connectors – Tests 27a to 27g*

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IEC 60512-28-100, *Connectors for electronic equipment – Tests and measurements – Part 28-100: Signal integrity tests up to 2 000 MHz on IEC 60603-7 and IEC 61076-3 series connectors – Tests 28a to 28g*

IEC 60603-7, *Connectors for electronic equipment – Part 7: Detail specification for 8-way, unshielded, free and fixed connectors*

IEC 60603-7-1, *Connectors for electronic equipment – Part 7-1: Detail specification for 8-way, shielded, free and fixed connectors*

IEC 60603-7-2, *Connectors for electronic equipment – Part 7-2: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 100 MHz*

IEC 60603-7-3, *Connectors for electronic equipment – Part 7-3: Detail specification for 8-way, shielded, free and fixed connectors, for data transmission with frequencies up to 100 MHz*

IEC 60603-7-4, *Connectors for electronic equipment – Part 7-4: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 250 MHz*

IEC 60603-7-5, *Connectors for electronic equipment – Part 7-5: Detail specification for 8-way, shielded, free and fixed connectors, for data transmissions with frequencies up to 250 MHz*

IEC 60603-7-41, *Connectors for electronic equipment – Part 7-41: Detail specification for 8-way, unshielded, free and fixed connectors, for data transmissions with frequencies up to 500 MHz*

IEC 60603-7-51, *Connectors for electronic equipment – Part 7-51: Detail specification for 8-way, shielded, free and fixed connectors, for data transmissions with frequencies up to 500 MHz*

IEC 60603-7-81, *Connectors for electronic equipment – Part 7-81: Detail specification for 8-way, shielded, free and fixed connectors, for data transmissions with frequencies up to 2 000 MHz*

IEC 61156-1, *Multicore and symmetrical pair/quad cables for digital communications – Part 1: Generic specification*

IEC 61156-9, *Multicore and symmetrical pair/quad cables for digital communications – Part 9: Cables for channels with transmission characteristics up to 2 GHz – Sectional specification*

IEC 61156-10, *Multicore and symmetrical pair/quad cables for digital communications – Part 10: Cables for cords with transmission characteristics up to 2 GHz – Sectional specification*

IEC 61169-16, *Radio-frequency connectors – Part 16: Sectional specification – RF coaxial connectors with inner diameter of outer conductor 7 mm (0,276 in) with screw coupling – Characteristics impedance 50 ohms (75 ohms) (type N)*

IEC 61935-1, *Specification for the testing of balanced and coaxial information technology cabling – Part 1: Installed balanced cabling as specified in ISO/IEC 11801 and related standards*

IEC 61935-2, *Specification for the testing of balanced and coaxial information technology cabling – Part 2: Cords as specified in ISO/IEC 11801 and related standards*

ISO/IEC 11801-1, *Information technology – Generic cabling for customer premises – Part 1: General requirements*

ITU-T Recommendation G.117, *Transmission aspects of unbalance about earth*

Withdrawn